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TID #: TID-00626

TIDA-00626 REV E1 Bill of Materials



Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1	Taluc	TIDA-00626	Any	Printed Circuit Board	i donagonolorono
2	-5V, 3.3V, 8.5V, 8V, ATP1, ATP2, CSB_TP, GND_TP, MUXout_TP, SCK_TP, SDI_TP, Vcc_TP1, Vtune_TP	13	White	5007	Keystone	Test Point, Compact, White, TH	White Compact Testpoint
3	C1	1	300pF	GRM1555C1E301JA01D	MuRata	CAP, CERM, 300 pF, 25 V, +/- 5%, C0G/NP0, 0402	402
4	C2, C28, C34	3	100pF	GRM1535C1H101JDD5D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0402	402
5	C3	1	6800pF	GRM155R71H682KA88D	MuRata	CAP, CERM, 6800 pF, 50 V, +/- 10%, X7R, 0402	402
6	C4, C6, C23, C25, C29, C31, C33, C36, C39, C47	10	0.1uF	C0402C104K4RACAUTO	Kemet	CAP, CERM, 0.1 μF, 16 V, +/- 10%, X7R, AEC-Q200 Grade 1, 0402	402
7	C5, C10, C14, C16, C20, C21, C65, C67	8	10uF	CL05A106MP5NUNC	Samsung Electro-Mechanics	CAP, CERM, 10 μF, 10 V, +/- 20%, X5R, 0402	402
8	C7, C11, C13, C17, C19, C22, C24, C26, C30, C32, C35, C40	12	1uF	C1005X5R1C105K050BC	TDK	CAP, CERM, 1 μF, 16 V, +/- 10%, X5R, 0402	402
9	C8, C57	2	1uF	C1608X7R1C105K	TDK	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	603
10	C9	1	10uF	C0805C106K8PACTU	Kemet	CAP, CERM, 10uF, 10V, +/-10%, X5R, 0805	805
11	C27, C41, C58, C62, C64, C66, C68	7	0.1uF	GRM155R71E104KE14D	MuRata	CAP, CERM, 0.1 μF, 25 V, +/- 10%, X7R, 0402	402
12	C37	1	0.047uF	GRM155R71E473KA88D	MuRata	CAP, CERM, 0.047 μF, 25 V, +/- 10%, X7R, 0402	402
13	C38	1	560pF	GRM1555C1E561JA01D	MuRata	CAP, CERM, 560 pF, 25 V, +/- 5%, C0G/NP0, 0402	402
14	C42, C49	2	10uF	TPSC106K025R0500	AVX	CAP, TA, 10 μF, 25 V, +/- 10%, 0.5 ohm, SMD	6032-28
15	C43, C48	2	1uF	12103C105KAT2A	AVX	CAP, CERM, 1 μF, 25 V, +/- 10%, X7R, 1210	1210
16	C44, C59	2	10uF	TPSA106K010R0900	AVX	CAP, TA, 10 μF, 10 V, +/- 10%, 0.9 ohm, SMD	3216-18
17	C45, C60	2	10uF	1206YC106KAT2A	AVX	CAP, CERM, 10 μF, 16 V, +/- 10%, X7R, 1206_190	1206_190
18	C46, C61	2	0.01uF	08055C103KAT2A	AVX	CAP, CERM, 0.01 μF, 50 V, +/- 10%, X7R, 0805	805
19	C50, C51, C52	3	2.2uF	0805YD225KAT2A	AVX	CAP, CERM, 2.2 μF, 16 V, +/- 10%, X5R, 0805	805
20	C53	1	1uF	0805YD105KAT2A	AVX	CAP, CERM, 1 μF, 16 V, +/- 10%, X5R, 0805	805
21	C54	1	10uF	GRM21BR61C106KE15L	MuRata	CAP, CERM, 10 μF, 16 V, +/- 10%, X5R, 0805	805
22	C55	1	4.7uF	C0805C475K8PACTU	Kemet	CAP, CERM, 4.7 μF, 10 V, +/- 10%, X5R, 0805	805
23	C56		680pF	CC0805KRX7R9BB681	Yageo America	CAP, CERM, 680 pF, 50 V, +/- 10%, X7R, 0805	805
24	C63	1	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603	603
25	D1, D3		Green	SML-LX0603GW-TR	Lumex	LED, Green, SMD	LED, GREEN, 0603
26	D2		40V	1N5819HW-7-F	Diodes Inc.	Diode, Schottky, 40 V, 1 A, SOD-123	SOD-123
27	FID1, FID2, FID3, FID4, FID5, FID6	6		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
28	H1, H2, H3, H4, H5, H6	6		TCBS-6-01	Richco Plastics	HEX STANDOFF SPACER, 9.53 mm	7.9x9.5 mm
29	J1	1		OSTTC022162	On-Shore Technology	Terminal Block, 2-pole, 200mil, TH	THD, 2-Leads, Body 10.16x7.6mm, Pitch 5.08mm

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
30	J2, J3	2	74.40	TSW-110-07-G-D	Samtec	Header, 100mil, 10x2, Gold, TH	10x2 Header
31	L1	1	18uH	ME3220-183KLB	Coilcraft	Inductor, Drum Core, Ferrite, 18 µH, 0.7 A, 0.7 ohm, SMD	ME3220
32	L2	1	18nH	LQG15HS18NJ02D	MuRata	Inductor, Multilayer, Air Core, 18 nH, 0.3 A, 0.36 ohm, SMD	0402 polarized
33	L3, L4	2	220 ohm	BLM18SG221TN1D	MuRata	Ferrite Bead, 220 ohm @ 100 MHz, 2.5 A, 0603	603
34	OSCinM, OSCinP, RFout	3		142-0701-851		Connector, SMT, End launch SMA 50 ohm	SMA
35	R1	1	12	CRCW040212R0JNED	Vishay-Dale	RES, 12, 5%, 0.063 W, 0402	402
36	R2, R3, R4, R5,	25	0	CRCW040212R03NED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	402
	R6, R7, R9, R19, R20, R21, R23, R25, R27, R32, R35, R36, R43, R44, R56, R57, R58, R61, R62, R65, R68	23			·		
37	R8	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	603
38	R10, R18, R24, R52	4	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	402
39	R11, R13, R15	3	18	CRCW040218R0JNED	Vishay-Dale	RES, 18, 5%, 0.063 W, 0402	402
40	R12, R14, R16, R31, R33, R37, R38, R50, R59, R60	10	12k	CRCW040212K0JNED	Vishay-Dale	RES, 12 k, 5%, 0.063 W, 0402	402
41	R17	1	680	CRCW0402680RJNED	Vishay-Dale	RES, 680, 5%, 0.063 W, 0402	402
42	R28	1	1.00k	MCR01MZPF1001	Rohm	RES, 1.00 k, 1%, 0.063 W, 0402	402
43	R29	1	10	CRCW040210R0JNED	Vishay-Dale	RES, 10, 5%, 0.063 W, 0402	402
44	R41	1	330	CRCW0402330RJNED	Vishay-Dale	RES, 330, 5%, 0.063 W, 0402	402
45	R42	1	150	CRCW0402150RFKED	Vishay-Dale	RES, 150, 1%, 0.063 W, 0402	402
46	R45, R66	2	120	CRCW0402120RJNED	Vishay-Dale	RES, 120, 5%, 0.063 W, 0402	402
47	R48	1	23.2k	CRCW080523K2FKEA	Vishay-Dale	RES, 23.2 k, 1%, 0.125 W, 0805	805
48	R49	1	13.3k	CRCW080513K3FKEA	Vishay-Dale	RES, 13.3 k, 1%, 0.125 W, 0805	805
49	R53	1	62.0k	RC0603FR-0762KL	Yageo America	RES, 62.0 k, 1%, 0.1 W, 0603	603
50	R54	1	10.5k	CRCW040210K5FKED	Vishay-Dale	RES, 10.5 k, 1%, 0.063 W, 0402	402
51	R55	1	6.81k	CRCW04026K81FKED	Vishay-Dale	RES, 6.81 k, 1%, 0.063 W, 0402	402
52	R63		82.5k	CRCW080582K5FKEA	Vishay-Dale	RES, 82.5 k, 1%, 0.125 W, 0805	805
53	R64	1	15.0k	ERJ-6ENF1502V	Panasonic	RES, 15.0 k, 1%, 0.125 W, 0805	805
54 55	R67 U1	1	511	RT0603BRD07511RL LMX2592	Yageo America Texas Instruments	RES, 511, 0.1%, 0.1 W, 0603 Dual output, 2-Phase, Stackable PMBLMX2592 test chip QFN 0.4mm-	603 RHA0040B
EC	U2	1		MAAD-011021-TR0500	MACOM	pitch 40-pin 6x6 PKG Digital Attenuator, 6-Bit, 0.5 dB LSB step DC - 30 GHz, PQFN-16	16-QFN
56 57	U3	1		NBB-312-T1	RF Micro Devices	Cascadable Broadband GaAs MMIC Amplifier DC to 12GHz, MPGA-9	9-MPGA
58	U4, U8	2		LP38798SD-ADJ/NOPB	Texas Instruments	Ultra Low Noise, 800 mA Linear Voltage Regulator for RF/Analog Circuits, DNT0012B	DNT0012B
59	U5	1		LMK61E2-SIAR	Texas Instruments	Ultra-Low Jitter Programmable Oscillator with Internal EEPROM, SIA0008B	SIA0008B
60	U6	1		LM2776DBVR	Texas Instruments	Switched Capacitor Inverter, DBV0006A	DBV0006A
61	U7	1		TPS61170DRVR	Texas Instruments	1.2A High Voltage Boost Converter in 2x2mm QFN Package, DRV0006A	DRV0006A
62	U9	1	SN74AHCT 244DW	SN74AHCT244DW	TI	IC, Octal Buffers/Drivers With 3-State Outputs	SOIC-20
63	uWire	1		52601-S10-8LF	FCI	Header (shrouded), 100mil, 5x2, Gold plated, SMD	SMT Header
64	Y1	1		CWX813-100.0M	Connor-Winfield	OSC 100.0000MHZ 3.3V +-25PPM SMD	7x1.3x5mm
65	Y2	1		CVPD-920-100	Crystek Corporation	VCXO, LVPECL 100.0 MHz, 3.3V, SMD	CVPD-920-6
66	R22, R26, R30, R34, R39, R40	0	12k	CRCW040212K0JNED	Vishay-Dale	RES, 12 k, 5%, 0.063 W, 0402	402

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